

# **EDB101 THRU EDB106**

### GLASS PASSIVATED SUPER FAST SILICON SURFACE MOUNT BRIDGE RECTIFIER VOLTAGE RANGE 50 to 400 Volts CURRENT 1.0 Ampere

#### **FEATURES**

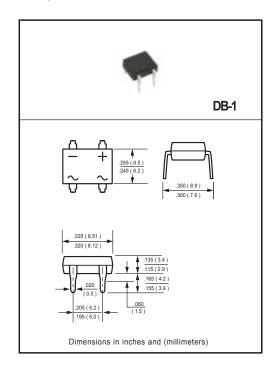
- \* Good for automatic insertion
- \* Surge overload rating 30 amperes peak
- \* Ideal for printed circuit board
- \* Reliable low cost construction utilizing molded
- \* Glass passivated device
- \* Polarity symbols molded on body
- \* Mounting position: Any
- \* Weight: 1.0 gram

#### **MECHANICAL DATA**

- \* UL listed the recongnized component directory,file #94233 \* Epoxy: Device has UL flammability classification 94V-O

#### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.



#### MAXIMUM RATINGS (At T<sub>A</sub> = 25°C unless otherwise noted)

RATINGS	SYMBOL	EDB101	EDB102	EDB103	EDB104	EDB105	EDB106	UNITS
Maximum Recurrent Peak Reverse Voltage	V <sub>RRM</sub>	50	100	150	200	300	400	Volts
Maximum RMS Bridge Input Voltage	V <sub>RMS</sub>	35	70	105	140	210	280	Volts
Maximum DC Blocking Voltage	V <sub>DC</sub>	50	100	150	200	300	400	Volts
Maximum Average Forward Output Current at T <sub>A</sub> = 55°C	I <sub>0</sub>	1.0						Amps
Peak Forward Surge Current 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	I <sub>FSM</sub>	30						Amps
Typical Thermal Resistance (Note 3)	R <sub>θJA</sub>	38						°C/W
	RøjL	12						
Typical Junction Capacitance (Note 2)	CJ	15 10				10	pF	
Operating and Storage Temperature Range	TJ,TSTG	-55 to + 150						°C

#### **ELECTRICAL CHARACTERISTICS** (At T<sub>A</sub> = 25°C unless otherwise noted)

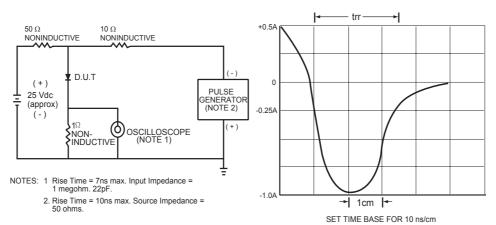
CHARACTERISTICS		SYMBOL	EDB101	EDB102	EDB103	EDB104	EDB105	EDB106	UNITS
Maximum Forward Voltage at 1.0A DC		V <sub>F</sub>	1.05 1.35 1.70					1.70	Volts
Maximum Reverse Current at Rated	@T <sub>A</sub> = 25°C	I_	5.0						μAmps
DC Blocking Voltage per element	@T <sub>A</sub> = 100°C	IR	100						μAmps
Maximum Reverse Recovery Time (Note 1)		trr	50						nSec

Note: 1.Test Conditions: I<sub>F</sub>=0.5A,I<sub>R</sub>=-1.0A,I<sub>RR</sub>=-0.25A.

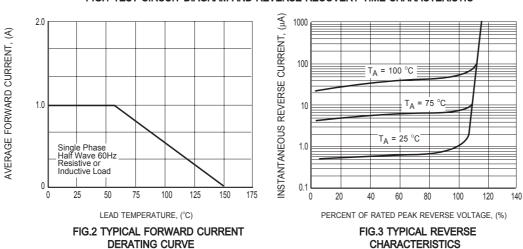
2.Measured at 1MHz and applied reverse voltage of 4.0 volts. 3.Thermal Resistance : Mounted on PCB.

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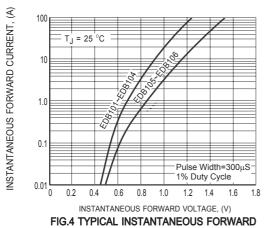
## RATING AND CHARACTERISTICS CURVES (EDB101 THRU EDB106)

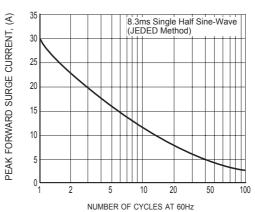


#### FIG.1 TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTIC



### RATING AND CHARACTERISTICS CURVES (EDB101 THRU EDB106)





**CHARACTERISTICS** 

FIG.5 MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

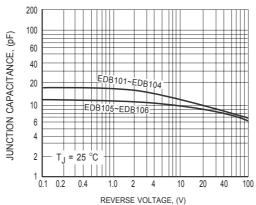


FIG.6 TYPICAL JUNCTION CAPACITANCE



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